

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a high-density chip scale package which is capable of increasing circuit density and expanding a circuit-formable zone. The high-density chip scale package comprises a die having a circuit pattern formed thereon, and a printed circuit board adapted for mounting the die thereon. The printed circuit board has an area 100 % to 150 % as large as an area of the die, and the printed circuit board has a circuit pattern formed thereon. On the die is mounted a heat sink for radiating heat from the die. Between the printed circuit board and the heat sink is filled an encapsulant for securely connecting the printed circuit board and the heat sink and shielding the printed circuit board from the outside.

15